

WPI Acc No: 2001-296523/ 200131

XRPX Acc No: N01-212514

Organic electroluminescent device has sealing layer for sealing organic electroluminescent laminated layer with transparent substrate through gel layer

Patent Assignee: TOYOTA JIDOSHA KK (TOYT )

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 2001068266	A	20010316	JP 99236748	A	19990824	200131 B

Priority Applications (No Type Date): JP 99236748 A 19990824

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 2001068266	A	8	H05B-033/04	

Abstract (Basic): JP 2001068266 A

NOVELTY - An organic electroluminescent (EL) laminated film (2) is formed on a transparent substrate (1). A gel layer (3) including absorbent (31) such as silicone gel and a gel component (32) is coated on EL laminated film. A sealing layer (4) connected to substrate, seals the EL laminated film with the substrate.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is also included for organic EL device manufacturing method.

USE - Organic electroluminescent device.

ADVANTAGE - Provision of moisture absorbent film provides excellent protection to film from moisture. Gel layer exhibits outstanding stores absorption effect towards sealing layer side. Since absorbent is dispersent around EL laminated layer, the generated heat gets distributed uniformly, therefore local thermal deterioration is prevented. Since absorbent is fixed layer, damage to EL layer is prevented,

DESCRIPTION OF DRAWING(S) - The figure shows the cross-sectional view of organic EL device.

Transparent substrate (1)

EL laminated film (2)

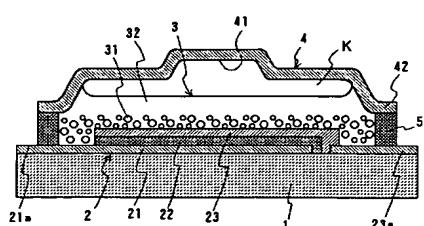
Gel layer (3)

Sealing layer (4)

Absorbent (31)

Gel component (32)

pp; 8 DwgNo 1/10



Title Terms: ORGANIC; ELECTROLUMINESCENT; DEVICE; SEAL; LAYER; SEAL;

aluminum hydroxide in the mixture, is 30  $\mu\text{m}$  or less.

USE - As synthetic resin board.

ADVANTAGE - The formation of bubbles due to aluminum hydroxide present in the mixture is prevented. The molded thermoplastic resin has high impact strength and large industrial value. When the molded thermoplastic resin is incinerated, the concentration of carbon monoxide produced in the waste gas is reduced.

pp; 5 DwgNo 0/0

Technology Focus:

TECHNOLOGY FOCUS - INORGANIC CHEMISTRY - Preferred Composition: The hydroscopic agent is calcium oxide and it does not contain particles having a diameter of 30  $\mu\text{m}$  or more.

POLYMERS - Preferred Resin: The thermoplastic resin is homo or copolymer of ethylene and propylene.

Title Terms: MANUFACTURE; THERMOPLASTIC; RESIN; SYNTHETIC; RESIN; BOARD; MIXTURE; CONTAIN; SPECIFIED; AMOUNT; HYDROXIDE; SPECIFIED; DIAMETER; THERMOPLASTIC; RESIN; HYDROSCOPIC; AGENT

Derwent Class: A17; A32; E33; Q32

International Patent Class (Main): C08L-101/00

International Patent Class (Additional): B65D-030/02; C08K-003/22; C08K-007/08; C08L-023/08; C08L-023/12; C08L-023/16

File Segment: CPI; EngPI

Manual Codes (CPI/A-N): A08-S08; A12-A04; E34-C02; E34-D01

Chemical Fragment Codes (M3):

\*01\* A313 A940 C101 C108 C550 C730 C801 C802 C804 C805 C807 M411 M782  
M904 M905 M910 Q130 Q140 R023 R036 R043 R02020-K R02020-M

\*02\* A220 A940 C108 C550 C730 C801 C802 C803 C804 C805 C807 M411 M782  
M904 M905 M910 Q130 Q140 R036 R043 R01503-K R01503-M

Polymer Indexing (PS):

<01>

\*001\* 018; R00326 G0044 G0033 G0022 D01 D02 D12 D10 D51 D53 D58 D82;  
R00964 G0044 G0033 G0022 D01 D02 D12 D10 D51 D53 D58 D83; H0000;  
H0317; H0011-R; S9999 S1434; P1172 P1161; P1150 ; P1343

\*002\* 018; ND07; B9999 B3601 B3554; B9999 B4831-R B4740; N9999 N6440-R;  
N9999 N6439; B9999 B4159 B4091 B3838 B3747; B9999 B4488 B4466;  
N9999 N5970-R; B9999 B5243-R B4740

\*003\* 018; R02020 D00 D67 F21 H- A1 3A 0- 6A; A999 A248-R

\*004\* 018; R01503 D00 F20 Ca 2A 0- 6A; A999 A022 A000; S9999 S1456-R

Derwent Registry Numbers: 1503-U; 2020-U

Specific Compound Numbers: R02020-K; R02020-M; R01503-K; R01503-M

Key Word Indexing Terms:

\*01\* 87080-0-0-0-CL 607-0-0-0-CL

WPI Acc No: 2001-047113/ 200106

XRXPX Acc No: N01-036217

Display device used in electrical/electronic devices, has airtight space which is formed between glass substrate and spacer of back plate

Patent Assignee: MITSUMI ELECTRIC CO LTD (DENA )

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 2000310958	A	20001107	JP 99120897	A	19990428	200106 B